

Description

This dual center tab Schottky rectifier is suited for high frequency switched mode power supplies.

Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	2 x 5A
V_{RRM}	150 V
$T_{j(max)}$	175 °C
V_F (Typ)	0.69 V

Features

- High junction temperature capability
- Good trade off between leakage current and forward voltage drop
- Low leakage current
- Avalanche capability specified
- Insulated package:
 - TO-220FPAB insulating voltage = 2000V_{RMS} sine
- ECOPACK®2 compliant component for D²PAK on demand

1 Characteristics

Table 2. Absolute ratings (limiting values per diode at $T_{amb} = 25^\circ\text{C}$ unless otherwise stated)

Symbol	Parameter				Value	Unit
V_{RRM}	Repetitive peak reverse voltage				150	V
$I_{F(RMS)}$	Forward rms current				10	A
$I_{F(AV)}$	Average forward current, $\delta = 0.5$, square wave	TO-220AB, D ² PAK	$T_c = 155^\circ\text{C}$	Per diode	5	A
		TO-220FPAB	$T_c = 145^\circ\text{C}$			
		TO-220AB, D ² PAK	$T_c = 150^\circ\text{C}$	Per device	10	
		TO-220FPAB	$T_c = 130^\circ\text{C}$			
I_{FSM}	Surge non repetitive forward current		$t_p = 10\text{ ms sinusoidal}$		120	A
$P_{ARM}^{(1)}$	Repetitive peak avalanche power		$t_p = 10\text{ }\mu\text{s}, T_j = 125^\circ\text{C}$		220	W
T_{stg}	Storage temperature range				-65 to + 175	°C
T_j	Maximum operating junction temperature ⁽²⁾				175	°C

1. For pulse time duration derating, please refer to [Figure 3](#). More details regarding the avalanche energy measurements and diode validation in the avalanche are provided in the application notes AN1768 and AN2025.

2. $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal parameters

Symbol	Parameter				Value	Unit
$R_{th(j-c)}$	Junction to case	TO-220AB, D ² PAK	Per diode	4	°C/W	
		TO-220FPAB		7		
		TO-220AB, D ² PAK	Total	2.4		
		TO-220FPAB		5.3		
$R_{th(c)}$	Coupling	TO-220AB, D ² PAK		0.7	V	
		TO-220FPAB		3.7		

When the diodes 1 and 2 are used simultaneously:

$$\Delta T_j(\text{diode 1}) = P(\text{diode 1}) \times R_{th(j-c)}(\text{Per diode}) + P(\text{diode 2}) \times R_{th(c)}$$

Table 4. Static electrical characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Typ	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$	-	-	2.0	μA
		$T_j = 125^\circ\text{C}$		-	0.40	2.0	mA
$V_F^{(2)}$	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 5\text{ A}$	-	-	0.92	V
		$T_j = 125^\circ\text{C}$		-	0.69	0.75	
		$T_j = 25^\circ\text{C}$	$I_F = 10\text{ A}$	-	-	1.0	
		$T_j = 125^\circ\text{C}$		-	0.79	0.85	

1. Pulse test: $t_p = 5\text{ ms}, \delta < 2\%$

2. Pulse test: $t_p = 380\text{ }\mu\text{s}, \delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 0.65 \times I_{F(AV)} + 0.02 \times I_{F}^2(RMS)$$

Figure 1. Average forward power dissipation versus average forward current (per diode)

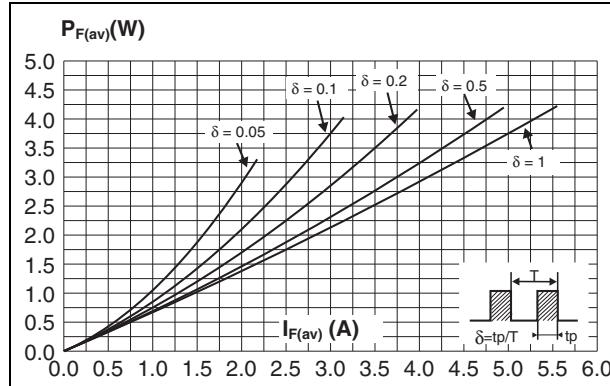


Figure 2. Average forward current versus ambient temperature ($\delta = 0.5$, per diode)

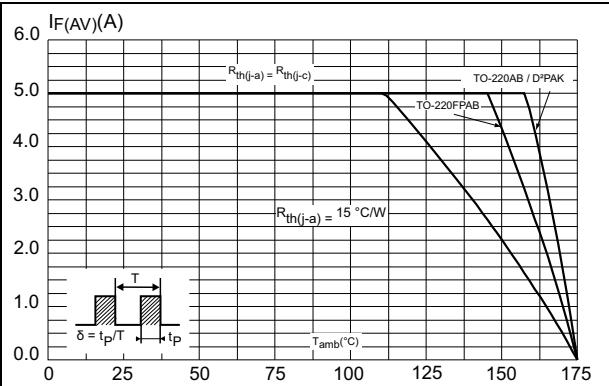


Figure 3. Normalized avalanche power derating versus pulse duration ($T_j = 125^\circ\text{C}$)

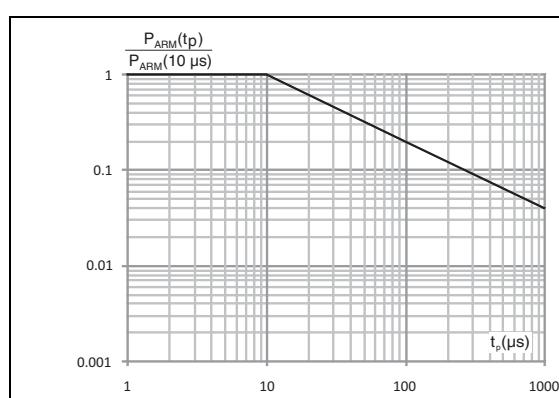


Figure 4. Reverse leakage current versus reverse voltage applied (typical values, per diode)

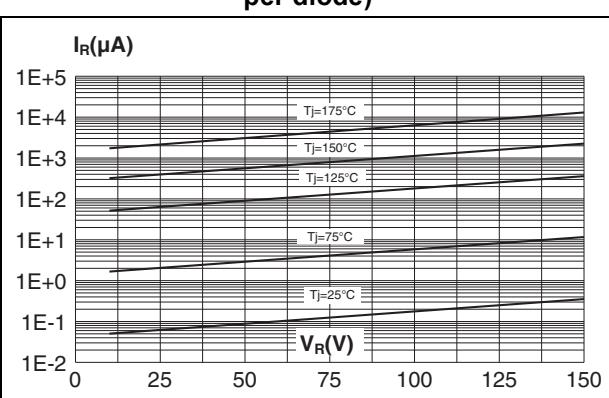


Figure 5. Relative variation of thermal impedance junction to case versus pulse duration (TO-220AB, D²PAK)

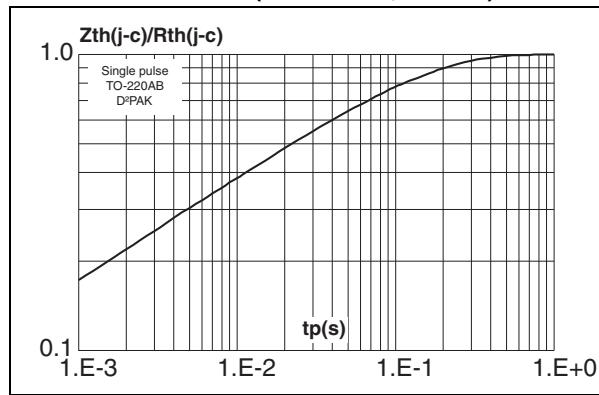


Figure 6. Relative variation of thermal impedance junction to case versus pulse duration (TO-220FPAB)

